

# Advanced Packaging Market Report: Trends, Forecast and Competitive Analysis

<https://marketpublishers.com/r/AAD48F1C805CEN.html>

Date: May 2024

Pages: 150

Price: US\$ 4,850.00 (Single User License)

ID: AAD48F1C805CEN

## Abstracts

**In Progress. Get it in 2 to 4 weeks by ordering today**

The future of the advanced packaging market looks promising with opportunities in the consumer electronics, automotive, industrial, aerospace and defense, healthcare industries. The global advanced packaging market is expected to grow with a CAGR of 10% to 12% from 2020 to 2025. The major drivers for this market are growing demands for high-performance gadgets and growth of the lithography manufacturing processes.

A total of XX figures / charts and XX tables are provided in more than 150 pages report is developed to help in your business decisions. Sample figures with some insights are shown below. To learn the scope, benefits, companies researched, and other details of the global advanced packaging market report, please download the report brochure.

advanced packaging

In this market, consumer electronics is expected to witness the highest growth over the forecast period. Growth in various segments of the advanced packaging market are given below:

The study includes trends and forecast for the global advanced packaging market by product type, end use industry, and region as follows:

By Product Type [Value (\$ Million) shipment analysis for 2014 – 2025]:

Flip-Chip Ball Grid Array Flip Chip CSP Wafer Level CSP 2.5D/3D Others

By End Use Industry [Value (\$ Million) shipment analysis for 2014 – 2025]:

Consumer ElectronicsAutomotive Industrial Aerospace & Defense Healthcare Others

By Region [Value (\$ Million) shipment analysis for 2014 – 2025]:

North AmericaUnited StatesCanada MexicoEuropeUnited KingdomSpainGermanyFranceAsia PacificChinaIndiaJapanThe Rest of the World Brazil

Some of the advanced packaging manufacturers profiled in this report include, Cardinal Matrix, Samsung Electronics Co., Ltd., Intel Corporation, Texas Instruments, Inc., and Qualcomm.

In this market, flip-chip ball grid array, flip chip CSP, wafer level CSP, 2.5D/3D and others are the major type used in advanced packaging.

Within this market, consumer electronics is expected to witness the highest growth over the forecast period due to increase in demand for smartphone and devices and Internet of Things (IoT).

Asia-Pacific will remain the largest region and it is also expected to witness the highest growth over the forecast period due to growing semiconductor market.

### Features of the Global Advanced Packaging Market

**Market Size Estimates:** Global advanced packaging market size estimation in terms of value (\$M) shipment.**Trend and Forecast Analysis:** Market trend (2014-2019) and forecast (2020-2025) by various segments and regions.**Segmentation Analysis:** Global advanced packaging market size by various segments, such as product type, end use industry, in terms of value.**Regional Analysis:** Global advanced packaging market breakdown by the North America, Europe, Asia Pacific, and Rest of the World.**Growth Opportunities:** Analysis of growth opportunities in different product type, end use industry, and region for the global advanced packaging market.**Strategic Analysis:** This includes M&A, new product development, and competitive landscape of the global advanced packaging market.**Analysis of competitive intensity of the industry based on Porter's Five Forces model.**

This report answers following key questions

- Q.1 What are some of the most promising potential, high-growth opportunities for the global advanced packaging market by product type (flip-chip ball grid array, flip chip CSP, wafer level CSP, 2.5D/3D, and others), end use industry (consumer electronics, automotive, industrial, aerospace & defense, healthcare and others), and region (North America, Europe, Asia Pacific, and Rest of the World)?
- Q. 2 Which segments will grow at a faster pace and why?
- Q.3 Which region will grow at a faster pace and why?
- Q.4 What are the key factors affecting market dynamics? What are the drivers and challenges of the market?
- Q.5 What are the business risks and threats to the market?
- Q.6 What are emerging trends in this market and the reasons behind them?
- Q.7 What are some changing demands of customers in the market?
- Q.8 What are the new developments in the market? Which companies are leading these developments?
- Q.9 Who are the major players in this market? What strategic initiatives are being implemented by key players for business growth?
- Q.10 What are some of the competitive products and processes in this market, and how big of a threat do they pose for loss of market share via material or product substitution?
- Q.11 What M & A activities did take place in the last five years in this market?

## Contents

### **1. EXECUTIVE SUMMARY**

### **2. MARKET BACKGROUND AND CLASSIFICATION**

2.1: Introduction, Background, and Classification

2.2: Supply Chain

2.3: Industry Drivers and Challenges

### **3. MARKET TRENDS AND FORECAST ANALYSIS FROM 2014 T 2025**

3.1: Macroeconomic Trends and Forecast

3.2: Global Advanced Packaging Market Trends and Forecast

3.3: Global Advanced Packaging Market by Product Type

3.3.1: Flip-Chip Ball Grid Array

3.3.2: Flip Chip CSP

3.3.3: Wafer Level CSP

3.3.4: 2.5D/3D

3.3.5: Others

3.4: Global Advanced Packaging Market by End Use Industry

3.4.1: Consumer Electronics

3.4.2: Automotive

3.4.3: Industrial

3.4.4: Aerospace & Defense

3.4.5: Healthcare

3.4.6: Others

### **4. MARKET TRENDS AND FORECAST ANALYSIS BY REGION**

4.1: Global Advanced Packaging Market by Region

4.2: North American Advanced Packaging Market

4.2.1: Market by Product Type: Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2.5D/3D and Others

4.2.2: Market by End Use Industry: Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare and Others

4.2.3: United States Advanced Packaging Market

4.2.4: Canadian Advanced Packaging Market

4.2.5: Mexican Advanced Packaging Market

#### 4.3: European Advanced Packaging Market

4.3.1: Market by Product Type: Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2.5D/3D and Others

4.3.2: Market by End Use Industry: Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare and Others

4.3.3: Germany Advanced Packaging Market

4.3.4: UK Advanced Packaging Market

4.3.5: Spain Advanced Packaging Market

4.3.6: France Advanced Packaging Market

#### 4.4: APAC Advanced Packaging Market

4.4.1: Market by Product Type: Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2.5D/3D and Others

4.4.2: Market by End Use Industry: Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare and Others

4.4.3: China Advanced Packaging Market

4.4.4: Japan Advanced Packaging Market

4.4.3: India Advanced Packaging Market

#### 4.5: ROW Advanced Packaging Market

4.5.1: Market by Product Type: Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2.5D/3D and Others

4.5.2: Market by End Use Industry: Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare and Others

4.5.3: Brazil Advanced Packaging Market

### **5. COMPETITOR ANALYSIS**

5.1: Product Portfolio Analysis

5.2: Market Share Analysis

5.3: Operational Integration

5.4: Geographical Reach

5.5: Porter's Five Forces Analysis

### **6. GROWTH OPPORTUNITIES AND STRATEGIC ANALYSIS**

6.1: Growth Opportunity Analysis

6.1.1: Growth Opportunities for Global Advanced Packaging Market by Product Type

6.1.2: Growth Opportunities for Global Advanced Packaging Market by End Use Industry

6.1.3: Growth Opportunities for Global Advanced packaging Market by Region

6.2: Emerging Trends in Global Advanced Packaging Market

6.3: Strategic Analysis

6.3.1: New Product Development

6.3.2: Capacity Expansion of Global Advanced Packaging Market

6.3.3: Mergers, Acquisitions and Joint Ventures in the Global Advanced Packaging Market

## **7. COMPANY PROFILES OF LEADING PLAYERS**

7.1: Cardinal Matrix

7.2: Samsung Electronics Co

7.3: Intel Corporation

7.4: Texas Instruments

7.5: Qualcomm, Inc.

## I would like to order

Product name: Advanced Packaging Market Report: Trends, Forecast and Competitive Analysis

Product link: <https://marketpublishers.com/r/AAD48F1C805CEN.html>

Price: US\$ 4,850.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

[info@marketpublishers.com](mailto:info@marketpublishers.com)

## Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/AAD48F1C805CEN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:  
Last name:  
Email:  
Company:  
Address:  
City:  
Zip code:  
Country:  
Tel:  
Fax:  
Your message:

**\*\*All fields are required**

Customer signature \_\_\_\_\_

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970